



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

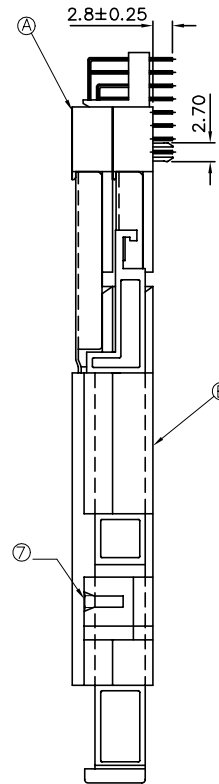
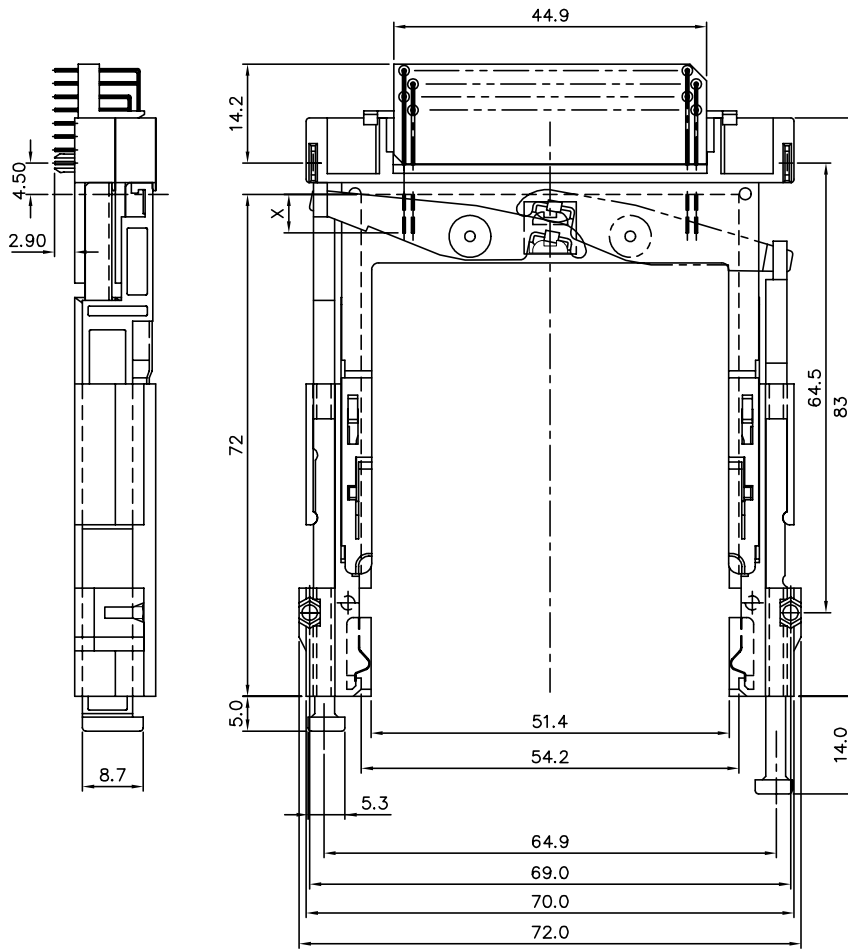
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



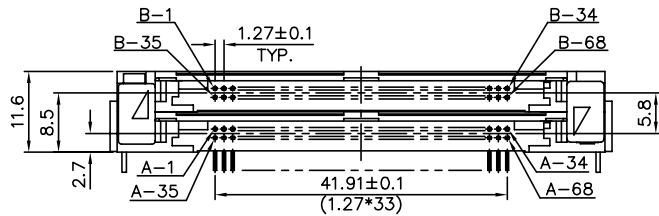
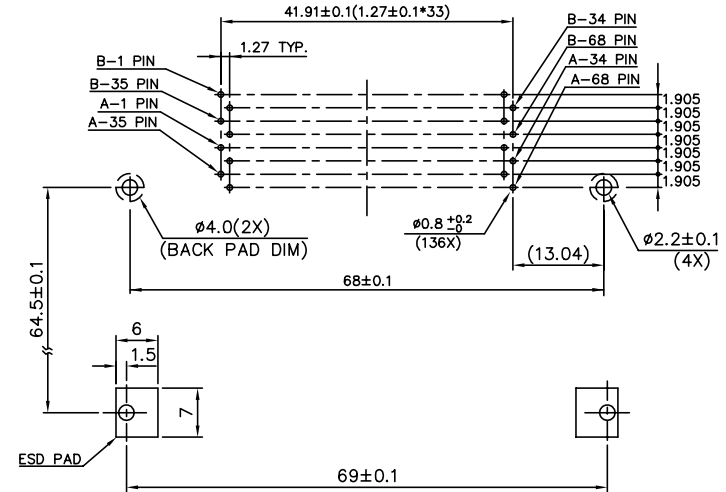
PRODUCT NO.
94721-001CA/001CALF



NOTES:

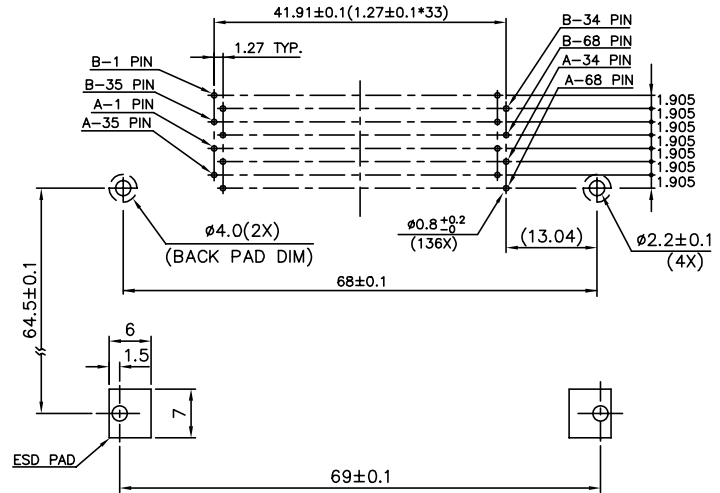
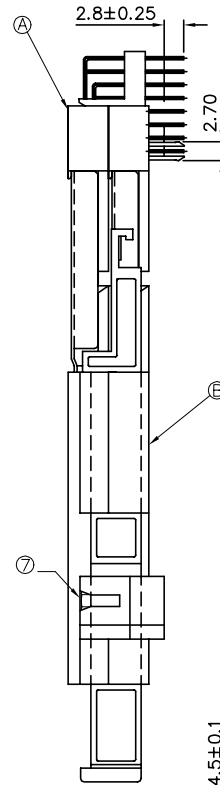
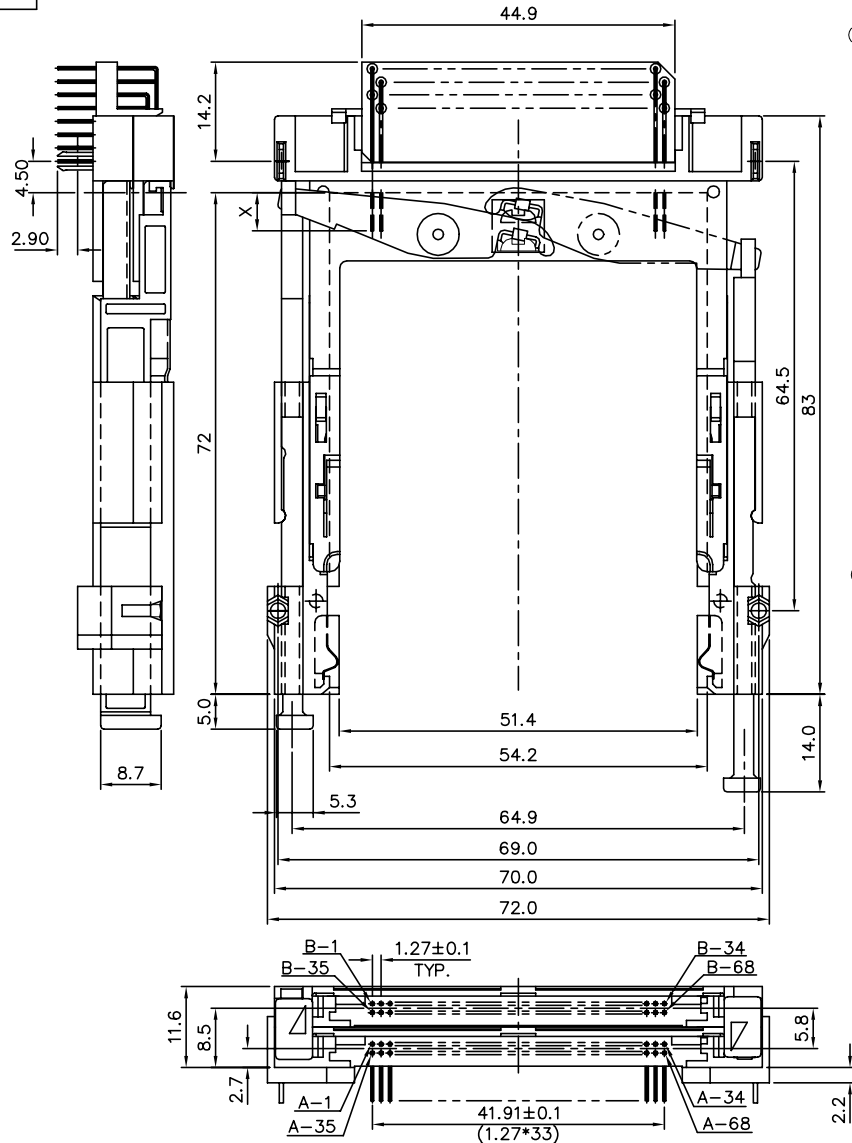
1. EJECT FORCE 3.5 Kg MAX.
2. ASS'Y PROCESS
 - 2.1 TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
3. EJECT TRAVEL: 9.0mm
4. MATERIAL
 - 4.1 PART (A) (HEADER ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN :COPPER ALLOY
 - 4.2 PART (B) (EJECT MECHANISM ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE :STAINLESS
EMI CONTACT:PHOSPHOR BRONZE
5. FINISH (PIN)
 - UNDER PLATING : 0.5µm MIN. Ni
 - CONTACT AREA : 0.076 µm MIN. GOLD
 - SOLDER TAIL : 2.5µm MIN. Sn-Pb
 - : 2.5µm MIN. PURE Sn (FOR -*****LF)
6.

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68
7. NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- 8 IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- 9 IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- 10 LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- 11 PRODUCT SPEC: 110-263



mat'l. code	surface	tolerance	projection	product family
ISD1302	ISD406	ISD1101	PCMCIA	
l t r e c n n o d r	date	tolerances unless otherwise specified	MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
K N05-174	WB 06/16/05	0.XX±0.3	MM	
L BX-N-007963	ZK 11/01/11	0.XX±0.13	scale: 1.5:1	
M BX-N-011435	ZK 04/23/12	0.XXX±0.05		
F T50218	WL 0726/95	dr C L FENG	04/06/94	dwg no
G T50236	WL 0815/95	engr JOSEPH HSIA	04/06/94	sheet 1 of 12
H T60040	WL 01/30/96	chr JOSEPH HSIA	04/06/94	size
J T60486	WL 12/09/96	app D K WANG	04/06/94	A4
sheet	revision	M M M M M M M M M M M M M M	type	Product Customer Drawing
index	sheet	1 2 3 4 5 6 7 8 9 10 11 12		

PRODUCT NO.
94721-002CA/002CALF



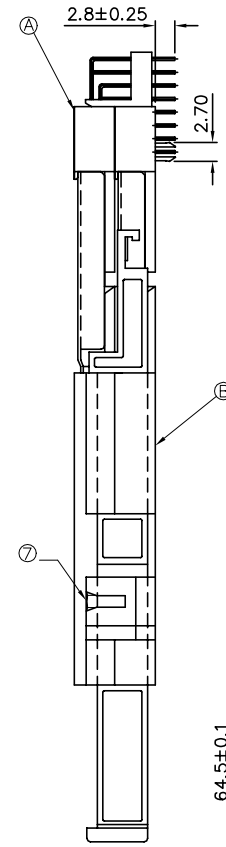
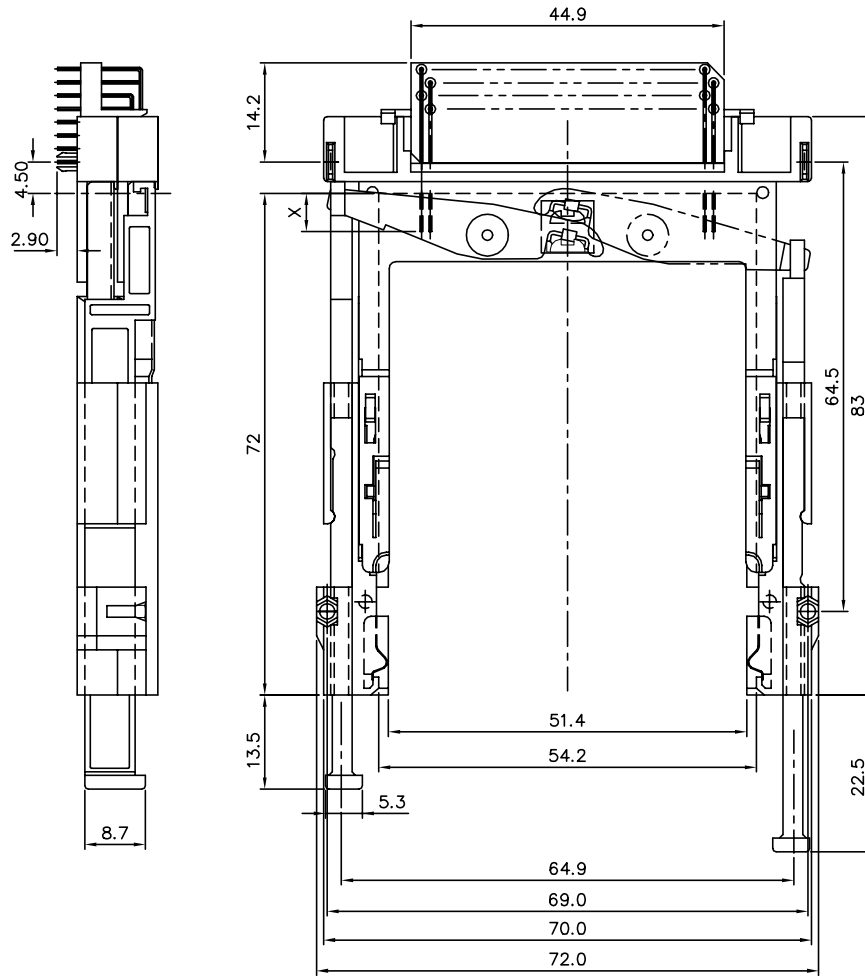
NOTES:

1. EJECT FORCE 3.5 Kg MAX.
2. ASS'Y PROCESS
- 2.1 TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
3. EJECT TRAVEL: 9.0mm
- (A) MATERIAL
- 4.1 PART (A) (HEADER ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN :COPPER ALLOY
- 4.2 PART (B) (EJECT MECHANISM ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE :STAINLESS
EMI CONTACT:PHOSPHOR BRONZE
5. FINISH (PIN)
UNDER PLATING :0.5µm MIN. NI
CONTACT AREA :0.076 µm MIN. GOLD
SOLDER TAIL : 2.5µm MIN. Sn-Pb
 : 2.5µm MIN. PURE Sn (FOR -*****LF)
6.

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68
- (B) NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- 8 IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- 9 IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- 10 LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- 11 PRODUCT SPEC: 110-263

mat'l. code	surface ISO1302	tolerance ISO406 ISO1101	projection	product family PCMCIA
l trechn nodr date	tolerances unless otherwise specified		MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
M	angle	0.X±0.3	scale: 5:1	dwg no 94721
	0°±2'	0.XX±0.13		sheet 2 of 12 size A4
		0.XXX±0.05		type Product Customer Drawing
dr c L FENG 04/06/94	engr JOSEPH HSIA 04/06/94	chr JOSEPH HSIA 04/06/94		
appd D K WANG 04/06/94				
sheet index	revision sheet			

PRODUCT NO.
94721-001DA/001DALF

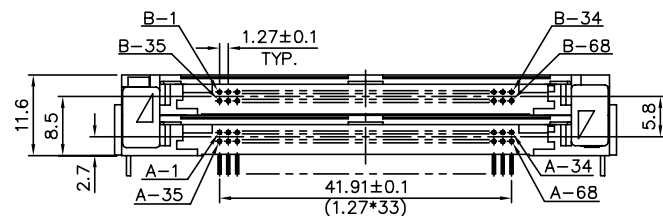
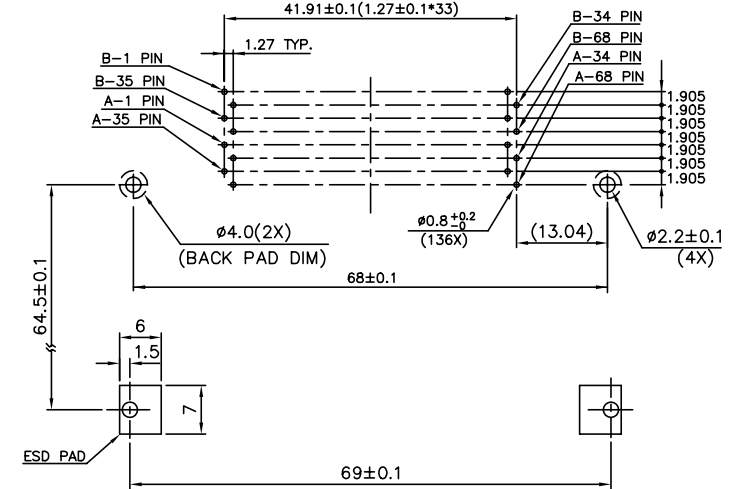


NOTES:

- EJECT FORCE 3.5 Kg MAX.
- ASSY PROCESS
 - TO MOUNT PART A ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART B WITH TWO SCREWS.
- EJECT TRAVEL: 9.0mm
- MATERIAL
 - PART A (HEADER ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN :COPPER ALLOY
 - PART B (EJECT MECHANISM ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE :STAINLESS
EMI CONTACT:PHOSPHOR BRONZE
- FINISH (PIN)
 - UNDER PLATING :0.5µm MIN. NI
CONTACT AREA :0.076 µm MIN. GOLD
SOLDER TAIL : 2.5µm MIN. Sn-Pb
SOLDER TAIL : 2.5µm MIN. PURE Sn (FOR -****LF)

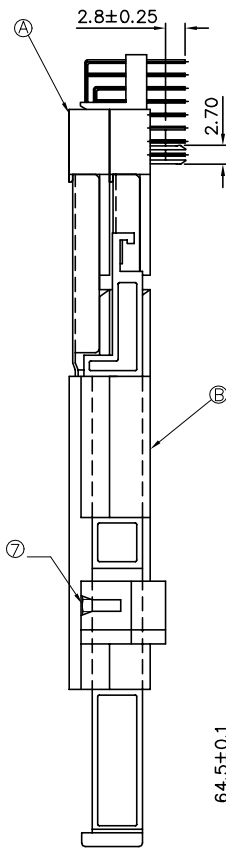
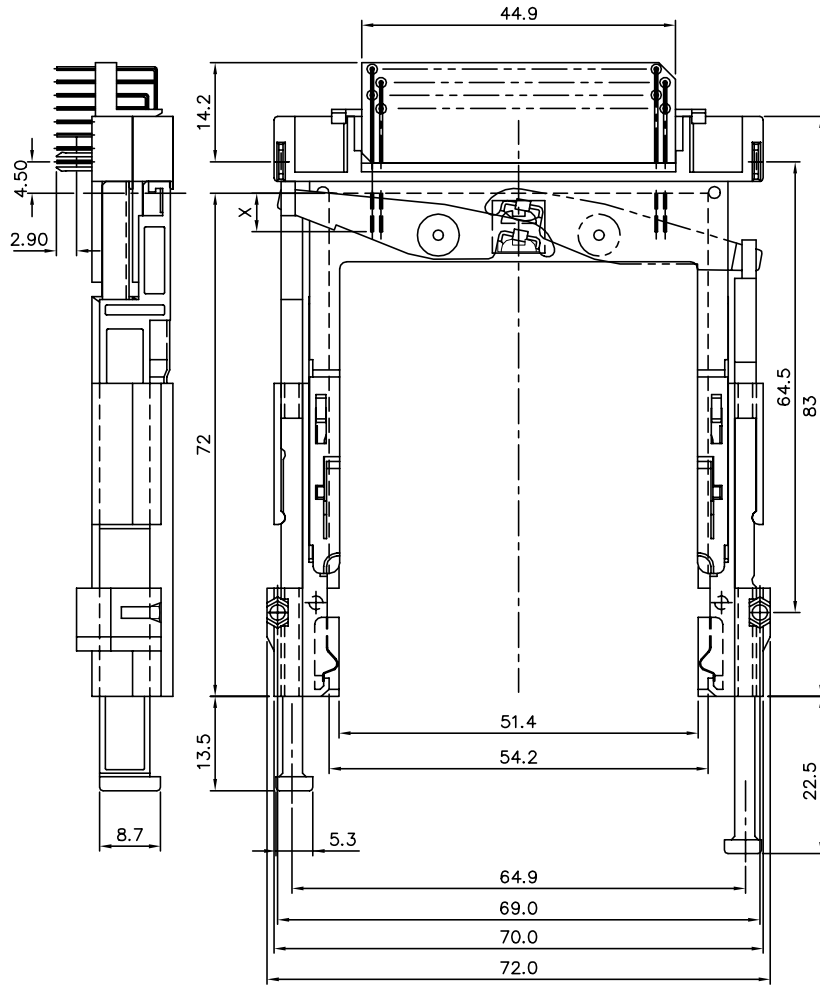
DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68

- NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT SPEC: 110-263



mat'l. code	surface ISO1302	tolerance ISO406 ISO1101	projection	product family PCMCIA
l'recn nodr date	tolerances unless otherwise specified	angle 0°±2'	MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
M		0.X±0.3	scale:1.5:1	dwg no 94721
		0.XX±0.13		sheet 3 of 12
		0.XXX±0.05		size A4
	dr c L FENG 04/06/94	eng JOSEPH HSIA 04/06/94	FCI	type Product Customer Drawing
	chr JOSEPH HSIA 04/06/94	app D K WANG 04/06/94		
sheet index	revision sheet			

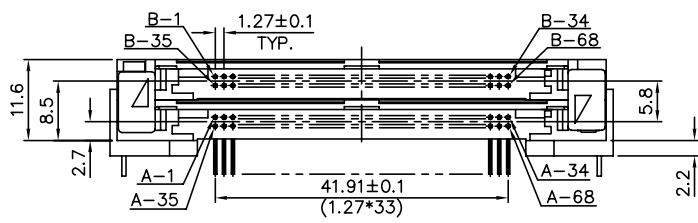
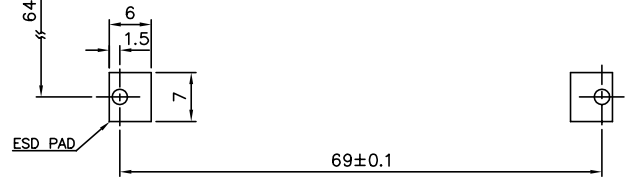
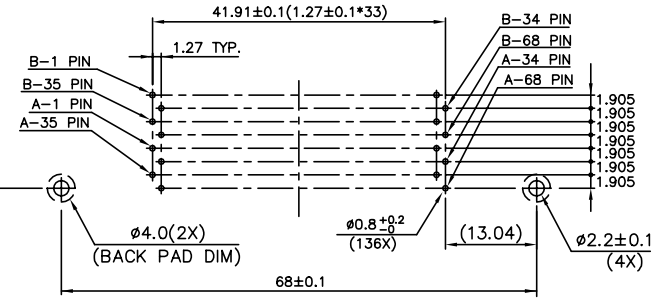
PRODUCT NO.
94721-002DA/002DALF



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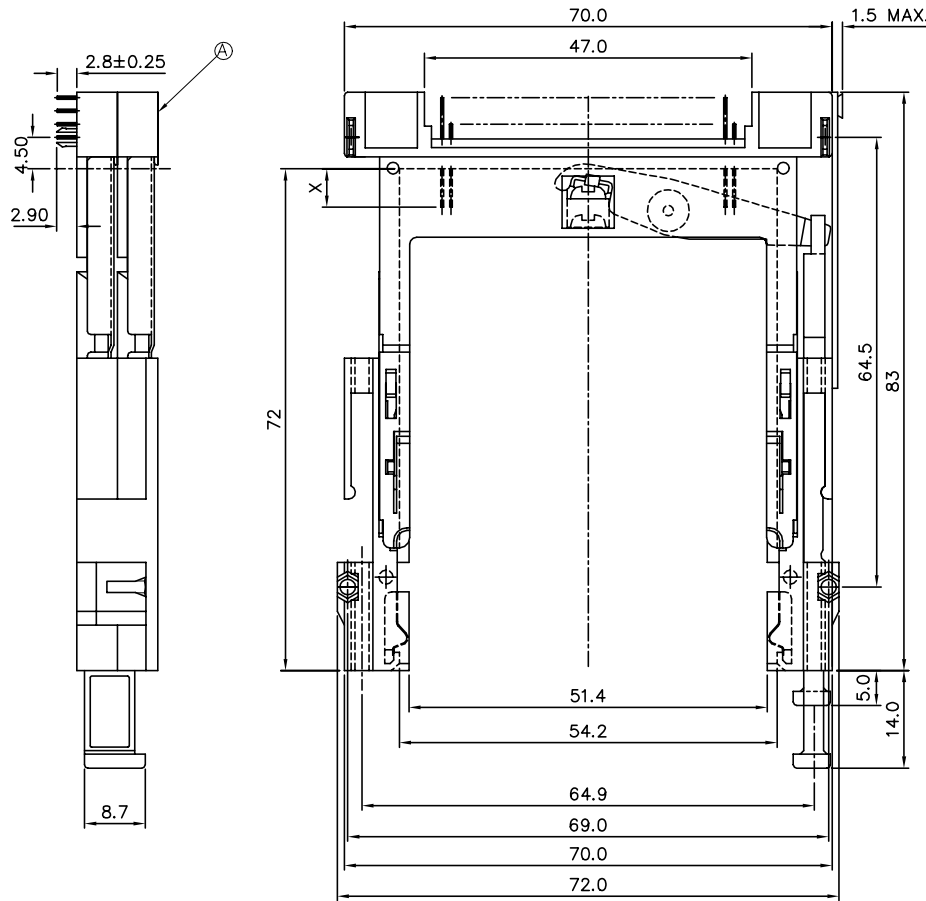
- 1. EJECT FORCE 3.5 Kg MAX.
- 2. ASS'Y PROCESS
 - 2.1 TO MOUNT PART ① ON PWB WITH HOLD DOWN(S1,S2) AND SOLDER THEN FIX PART ② WITH TWO SCREWS.
- 3. EJECT TRAVEL: 9.0mm
- ④ MATERIAL
 - 4.1 PART ① (HEADER ASS'Y)
 - PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
 - PIN : COPPER ALLOY
 - 4.2 PART ② (EJECT MECHANISM ASS'Y)
 - PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
 - PLATE : STAINLESS
 - EMI CONTACT: PHOSPHOR BRONZE
- 5. FINISH (PIN)
 - UNDER PLATING : 0.5µm MIN. Ni
 - CONTACT AREA : 0.076 µm MIN. GOLD
 - SOLDER TAIL : 2.5µm MIN. Sn-Pb
 - : 2.5µm MIN. PURE Sn (FOR -*****LF)
- 6.

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68
- ⑦ NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- 8 IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- 9 IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- 10 LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- 11 PRODUCT SPEC: 110-263



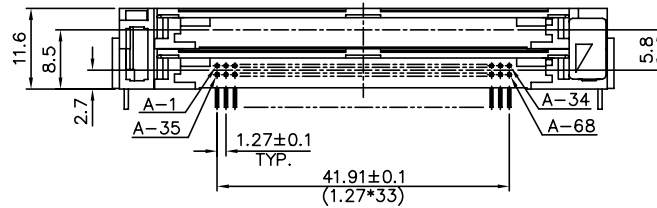
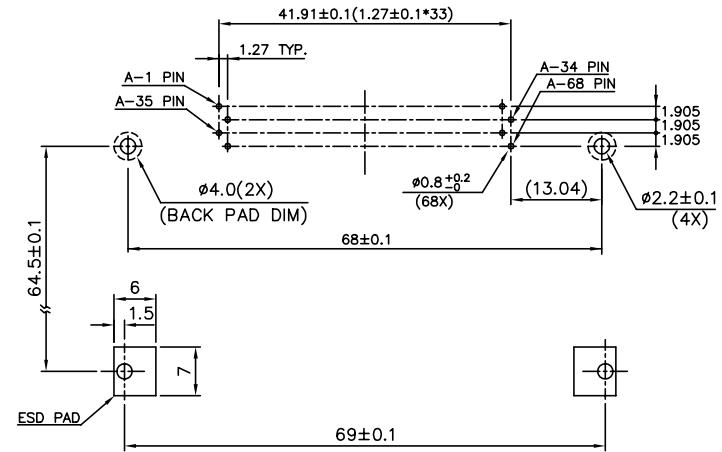
mat'l. code	surface	tolerance	projection	product family
	ISD1302	ISD406 ISD1101		PCMCIA
l tr ecn nodr	date	tolerances unless otherw	specificat	title
M		0.X±0.3	MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
		0.XX±0.13	scale 1.5:1	dwg no 94721 sheet 4 of 12 size A4
		0'±2'		type Product Customer Drawing
	dr	C L FENG 04/06/94		
	eng	JOSEPH HSIA 04/06/94		
	chr	JOSEPH HSIA 04/06/94		
	app	D K WANG 04/06/94		
sheet index	revision sheet			

PRODUCT NO.
94721-003CA/003CALF



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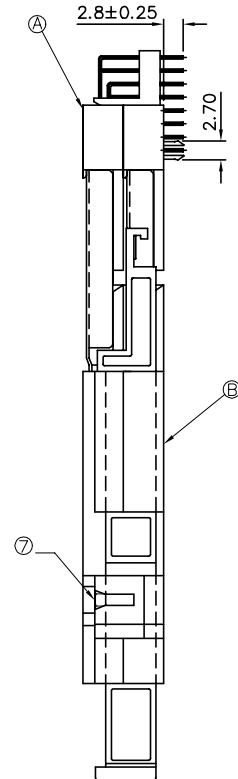
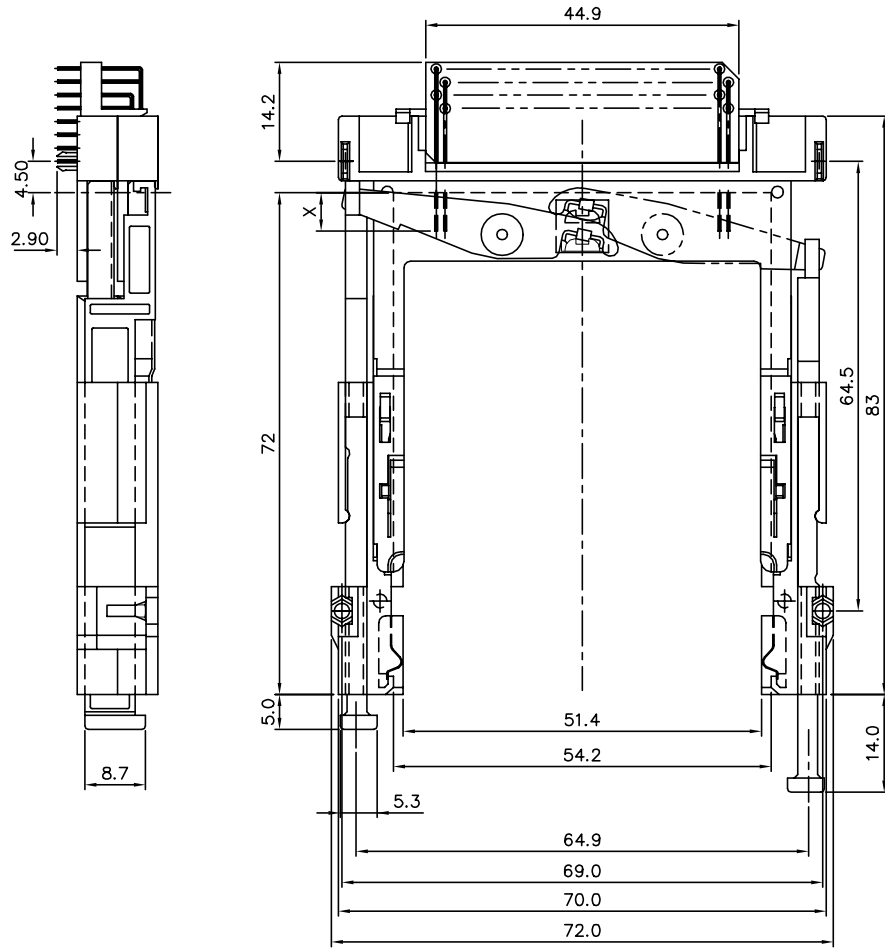
- EJECT FORCE 3.5 Kg MAX.
- ASS'Y PROCESS
- TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
- EJECT TRAVEL: 9.0mm
- (A) MATERIAL
 - PART (A) (HEADER ASS'Y)
PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : COPPER ALLOY
 - PART (B) (EJECT MECHANISM ASS'Y)
PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE : STAINLESS
EMI CONTACT: PHOSPHOR BRONZE
- FINISH (PIN)
UNDER PLATING : 0.5µm MIN. NI
CONTACT AREA : 0.076 µm MIN. GOLD
SOLDER TAIL : 2.5µm MIN. Sn-Pb
 : 2.5µm MIN. PURE Sn (FOR -*****LF)
- | DIM "X" | 4.25±0.1 | 3.5±0.1 | 5.0±0.1 |
|------------|----------|---------|------------------|
| PIN NUMBER | OTHERS | 36,67 | 1,17,34,35,51,68 |
- NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT SPEC: 110-263



mat'l. code	surface	tolerance	projection	product family
	ISO1302	ISO406 ISO1101		PCMCIA
l trechn nodr date	tolerances unless otherwise specified			
M	angle	0.X±0.3	MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
	0°±2'	0.XX±0.13	scale: 1.5:1	
		0.XXX±0.05		
dr	c L FENG	04/06/94		dwg no
engr	JOSEPH HSIA	04/06/94		sheet 5 of 12
chr	JOSEPH HSIA	04/06/94		size
appd	D K WANG	04/06/94		A4
sheet index	revision sheet			type Product Customer Drawing



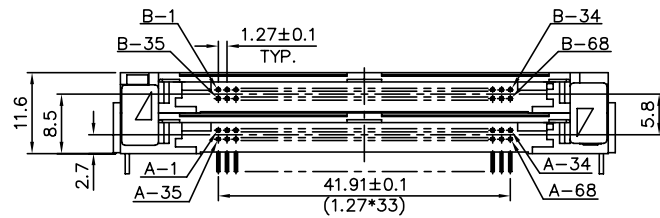
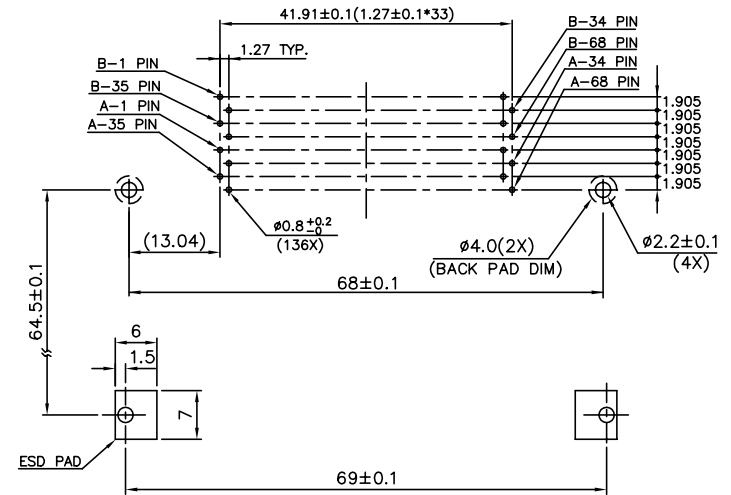
PRODUCT NO.
94721-004CA/004CALF



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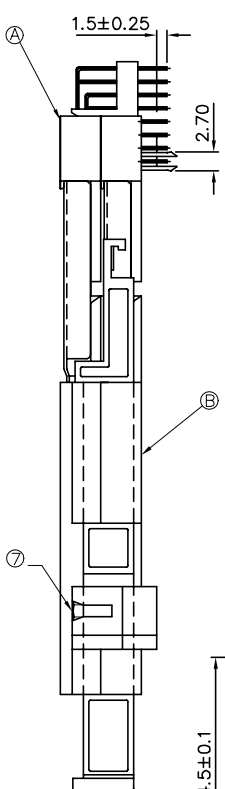
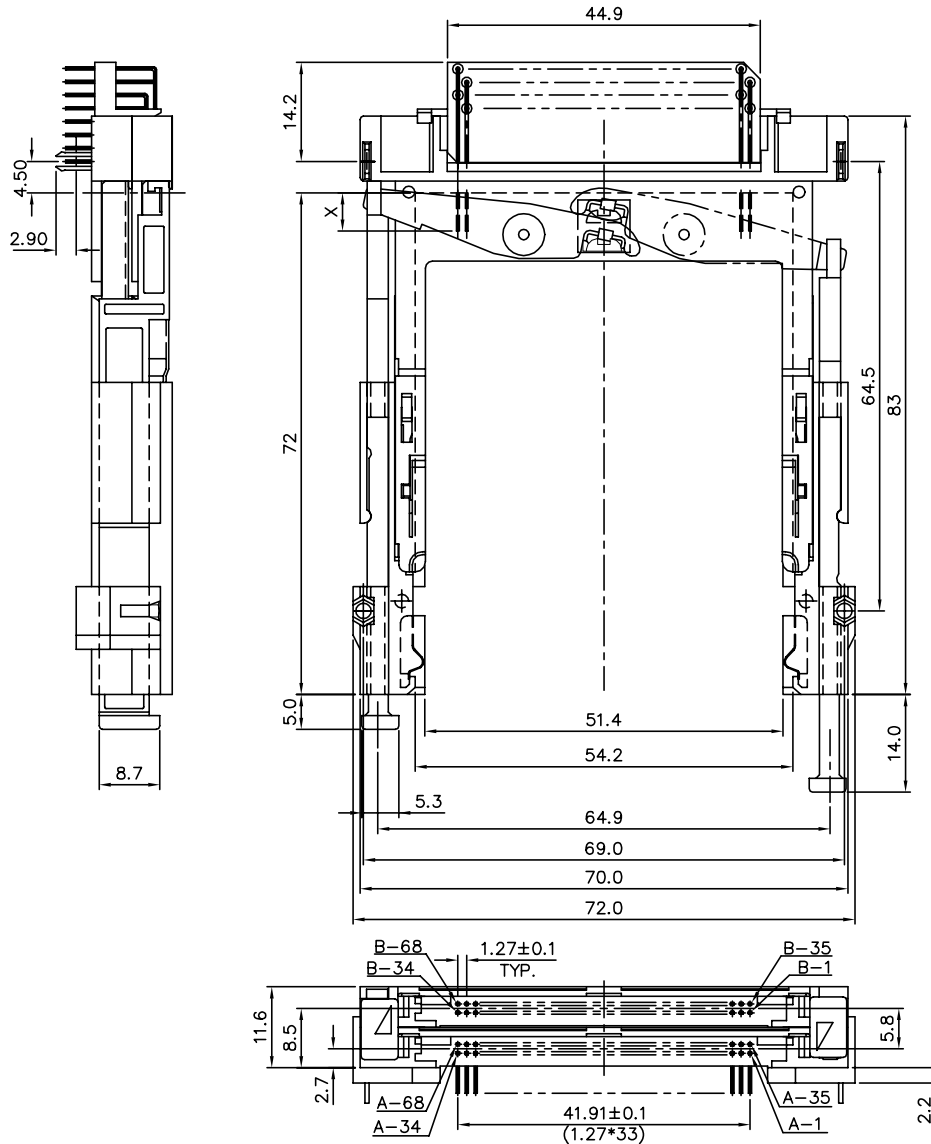
1. EJECT FORCE 3.5 Kg MAX.
2. ASS'Y PROCESS
- 2.1 TO MOUNT PART Ⓐ ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART Ⓑ WITH TWO SCREWS.
3. EJECT TRAVEL: 9.0mm
- Ⓐ MATERIAL
- 4.1 PART Ⓐ (HEADER ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN :PHOSPHOR BRONZE
- 4.2 PART Ⓑ (EJECT MECHANISM ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE :STAINLESS
EMI CONTACT:PHOSPHOR BRONZE
5. FINISH (PIN)
UNDER PLATING :0.5µm MIN. NI
CONTACT AREA :0.076 µm MIN. GOLD
SOLDER TAIL : 2.5µm MIN. Sn-Pb
: 2.5µm MIN. PURE Sn (FOR -*****LF)
6.

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68
- Ⓒ NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- 8 IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM THICK CIRCUIT BOARD.
- 9 IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- 10 LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- 11 PRODUCT SPEC: 110-263



mat'l. code	surface ISO1302	tolerance ISO406 ISO1101	projection	product family PCMCIA
l'recn nodr date	tolerances unless otherwise specified		MM	title 68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
M	angle	0.X±0.3	scale:5:1	dwg no 94721
	0°±2'	0.XX±0.13		sheet 6 of 12 size A4
	dr c L FENG	04/06/94		type Product Customer Drawing
	eng JOSEPH HSIA	04/06/94		
	chr JOSEPH HSIA	04/06/94		
	app D K WANG	04/06/94		
sheet index	revision sheet			

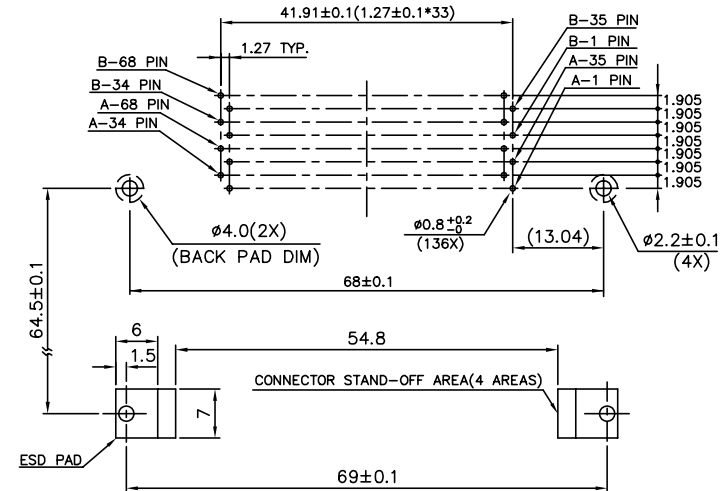
PRODUCT NO.
94721-105CA/105CALF



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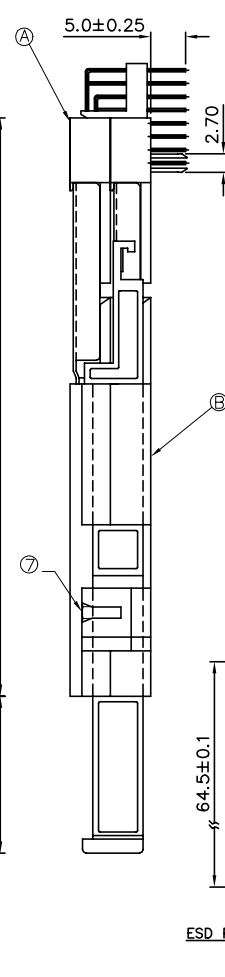
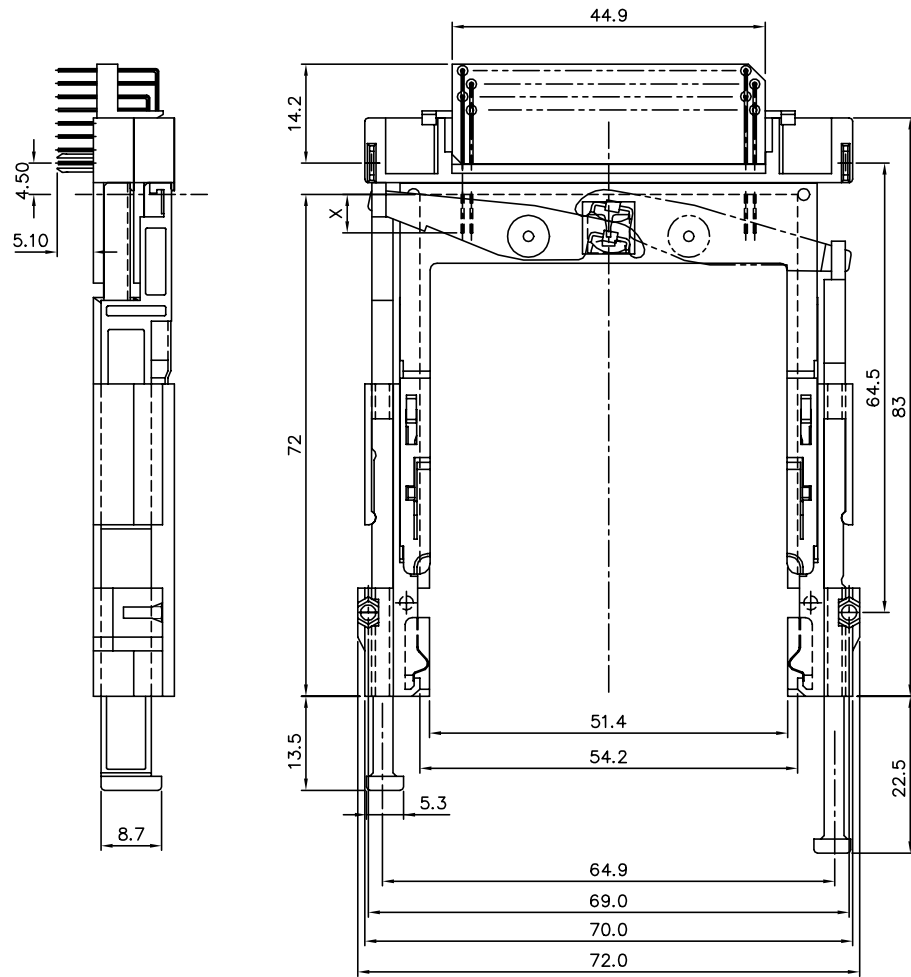
1. EJECT FORCE 3.5 Kg MAX.
2. ASSY PROCESS
 - 2.1 TO MOUNT PART ① ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART ② WITH TWO SCREWS.
3. EJECT TRAVEL: 9.0mm
- ④ MATERIAL
 - 4.1 PART ① (HEADER ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN :PHOSPHOR BRONZE
 - 4.2 PART ② (EJECT MECHANISM ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE :STAINLESS
EMI CONTACT:PHOSPHOR BRONZE
5. FINISH (PIN)
 - UNDER PLATING :0.5µm MIN. NI
 - CONTACT AREA :0.076 µm MIN. GOLD
 - SOLDER TAIL : 2.5µm MIN. Sn-Pb
 - : 2.5µm MIN. PURE Sn (FOR *****LF)
6.

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68
- ⑦ NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- 8 IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- 9 IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- 10 LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- 11 PRODUCT SPEC: 110-263



mat'l. code	surface ISO1302 ✓	tolerance ISO406 ISO1101	projection 	product family PCMCIA
l'tecn nodr	date	tolerances unless otherwise specified	MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
M		angle 0°±2'	scale:1.5:1	dwg no
		dr C L FENG 04/06/94		sheet 7 of 12
		engr JOSEPH HSIA 04/06/94		size A4
		chr JOSEPH HSIA 04/06/94		94721
		app D K WANG 04/06/94		type Product Customer Drawing
sheet index	revision sheet			

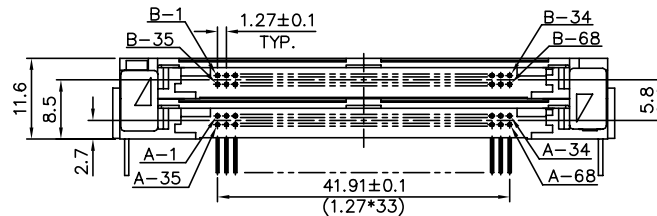
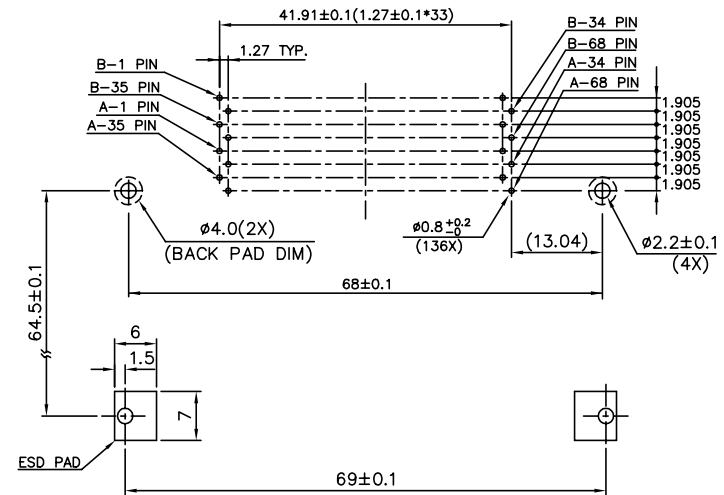
PRODUCT NO.
94721-003DA/003DALF



NOTES:

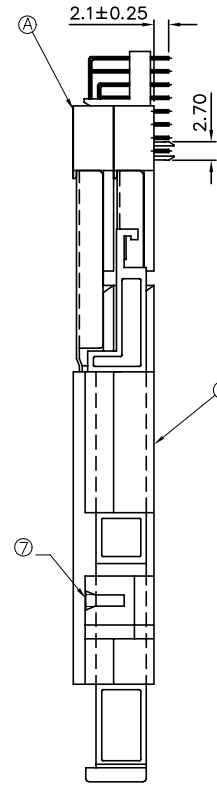
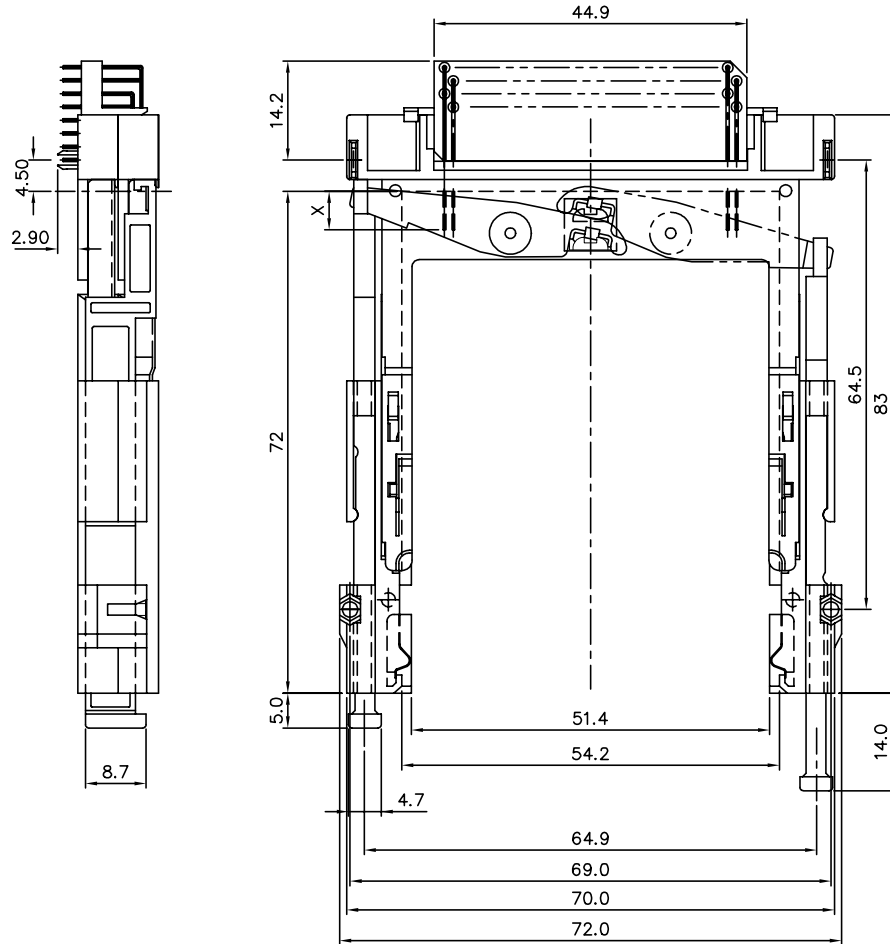
1. EJECT FORCE 3.5 Kg MAX.
2. ASSY PROCESS
 - 2.1 TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
3. EJECT TRAVEL: 9.0mm
4. MATERIAL
 - 4.1 PART (A) (HEADER ASS'Y)
PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : COPPER ALLOY
 - 4.2 PART (B) (EJECT MECHANISM ASS'Y)
PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE : STAINLESS
EMI CONTACT: PHOSPHOR BRONZE
5. FINISH (PIN)
 - UNDER PLATING : 0.5µm MIN. NI
 - CONTACT AREA : 0.076 µm MIN. GOLD
 - SOLDER TAIL : 2.5µm MIN. Sn-Pb
 - SOLDER TAIL : 2.5µm MIN. PURE Sn (FOR -*****LF)
6.

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68
7. NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
8. IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
9. IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
10. LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
11. PRODUCT SPEC: 110-263



mat'l. code	surface ISO1302	tolerance ISO406 ISO1101	projection	product family PCMCIA
l trechn nodr date	tolerances unless otherwise specified		MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
M	angle 0°±2'	0.X±0.3 0.XX±0.13 0.XXX±0.05	scale: 5:1	sheet 8 of 12 size A4
dr	c L FENG	04/06/94		dwg no 94721
eng	JOSEPH HSIA	04/06/94		type Product Customer Drawing
chr	JOSEPH HSIA	04/06/94		
app	D K WANG	04/06/94		
sheet index	revision sheet			

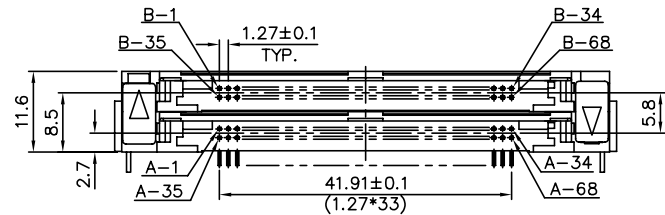
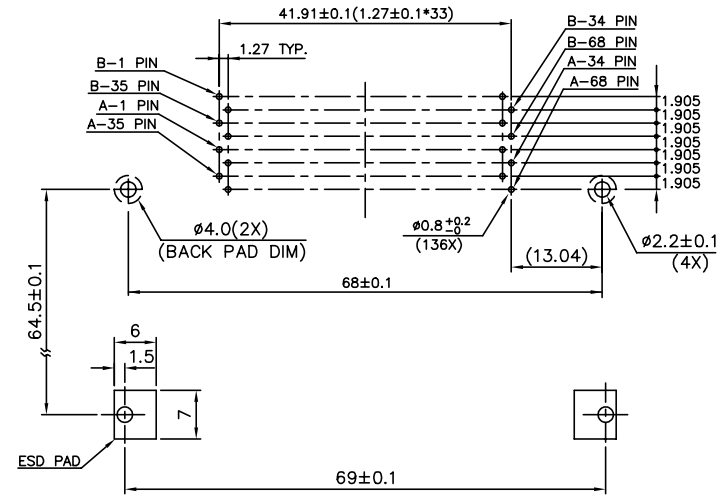
PRODUCT NO.
94721-005CA/005CALF



NOTES:

1. EJECT FORCE 3.5 Kg MAX.
2. ASS'Y PROCESS
- 2.1 TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
3. EJECT TRAVEL: 9.0mm
4. MATERIAL
- 4.1 PART (A) (HEADER ASS'Y)
PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : COPPER ALLOY
- 4.2 PART (B) (EJECT MECHANISM ASS'Y)
PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE : STAINLESS
EMI CONTACT: PHOSPHOR BRONZE
5. FINISH (PIN)
UNDER PLATING : 0.5µm MIN. Ni
CONTACT AREA : 0.076 µm MIN. GOLD
SOLDER TAIL : 2.5µm MIN. Sn-Pb
 : 2.5µm MIN. PURE Sn (FOR -*****LF)
6.

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68
7. NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
8. IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
9. IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
10. LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
11. PRODUCT SPEC: 110-263



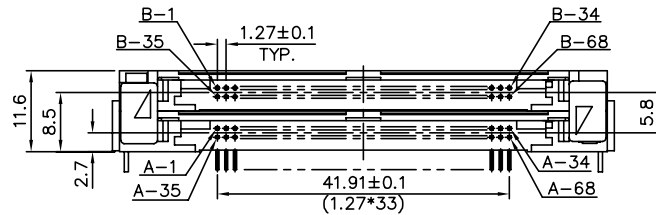
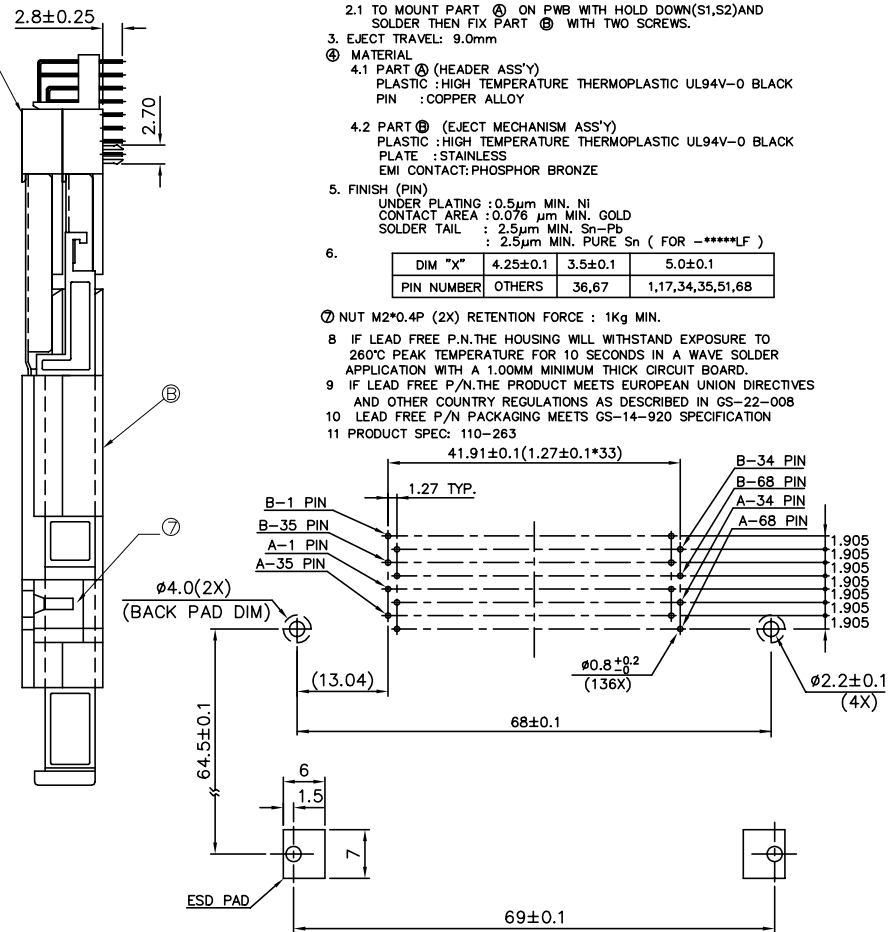
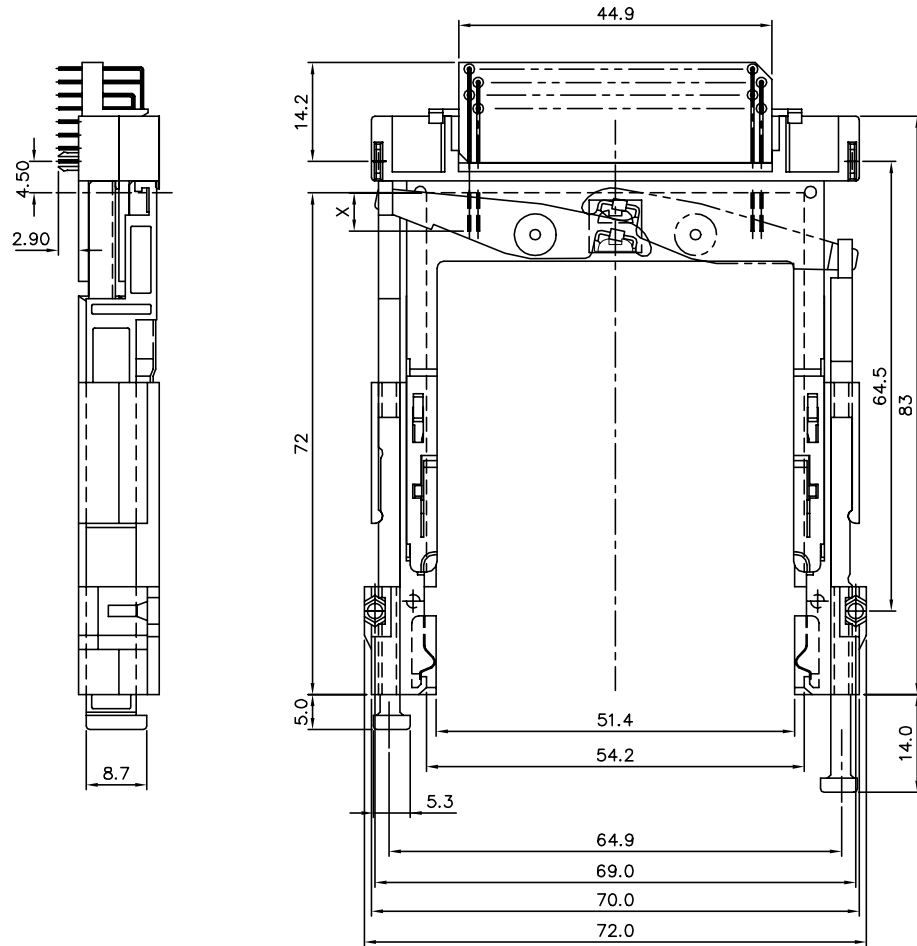
mat'l. code	surface ISO1302	tolerance ISO406 ISO1101	projection	product family PCMCIA
ltr ecn nodr date	tolerances unless otherwise specified		MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
M	angle	0.X±0.3	scale: 5:1	dwg no 94721
	0°±2'	0.XX±0.13		sheet 9 of 12 size A4
		0.XXX±0.05		type Product Customer Drawing
dr c L FENG 04/06/94	engr JOSEPH HSIA 04/06/94			
chr JOSEPH HSIA 04/06/94	appr D K WANG 04/06/94			
sheet index	revision sheet			

PRODUCT NO.
94721-006CA/006CALF

NOTES:

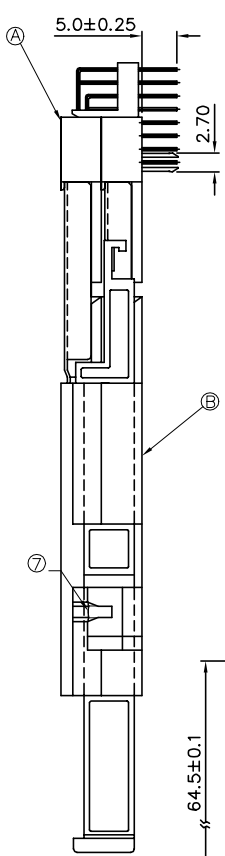
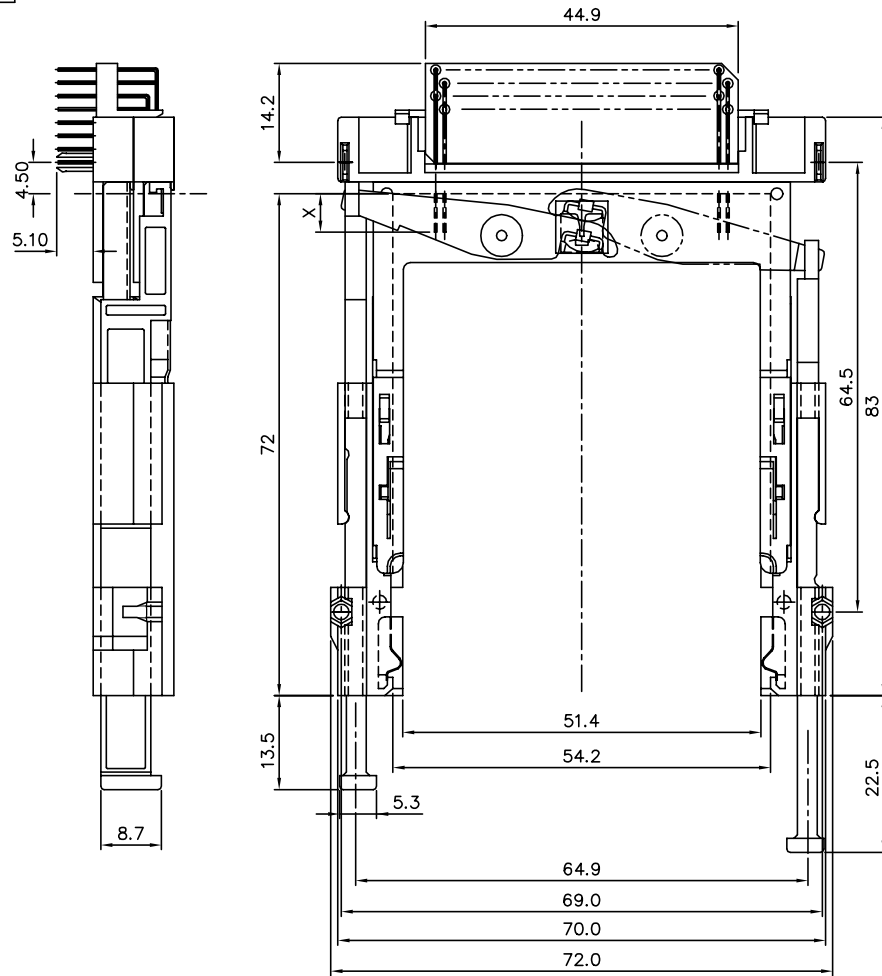
1. EJECT FORCE 3.5 Kg MAX.
2. ASS'Y PROCESS
2.1 TO MOUNT PART ④ ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART ③ WITH TWO SCREWS.
3. EJECT TRAVEL: 9.0mm
- ④ MATERIAL
4.1 PART ④ (HEADER ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN :COPPER ALLOY
- 4.2 PART ③ (EJECT MECHANISM ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE :STAINLESS
EMI CONTACT:PHOSPHOR BRONZE
5. FINISH (PIN)
UNDER PLATING :0.5µm MIN. NI
CONTACT AREA :0.076 µm MIN. GOLD
SOLDER TAIL : 2.5µm MIN. Sn-Pb
SOLDER TAIL : 2.5µm MIN. PURE Sn (FOR -****LF)
6.

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68
- ⑦ NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- B IF LEAD FREE P/N,THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- 9 IF LEAD FREE P/N,THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- 10 LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- 11 PRODUCT SPEC: 110-263



mat'l. code	surface	tolerance	projection	product family
	ISO1302	ISO406 ISO1101		PCMCIA
l'recn nodr date	tolerances unless otherwise specified			
M	angle	0.X±0.3	MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
	0°±2'	0.XXX±0.13	scale:1.5:1	
	dr	C L FENG 04/06/94		dwg no sheet no of 12 size
	engr	JOSEPH HSIA 04/06/94		94721 A4
	chr	JOSEPH HSIA 04/06/94		
	appd	D K WANG 04/06/94		
sheet index	revision sheet			type Product Customer Drawing

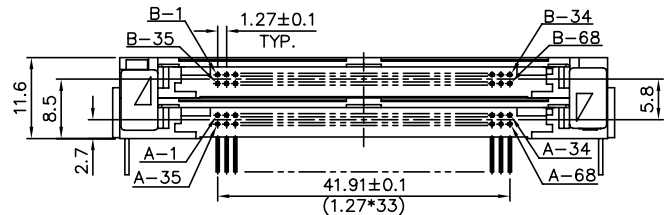
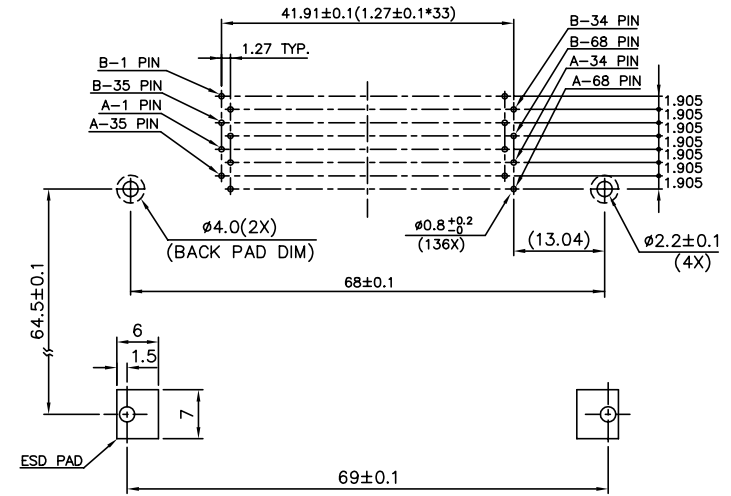
PRODUCT NO.
94721-004DA/004DALF



NOTES:

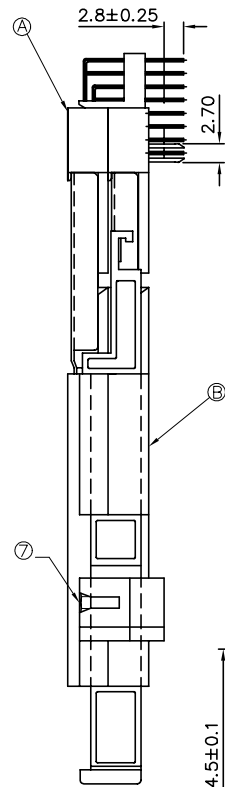
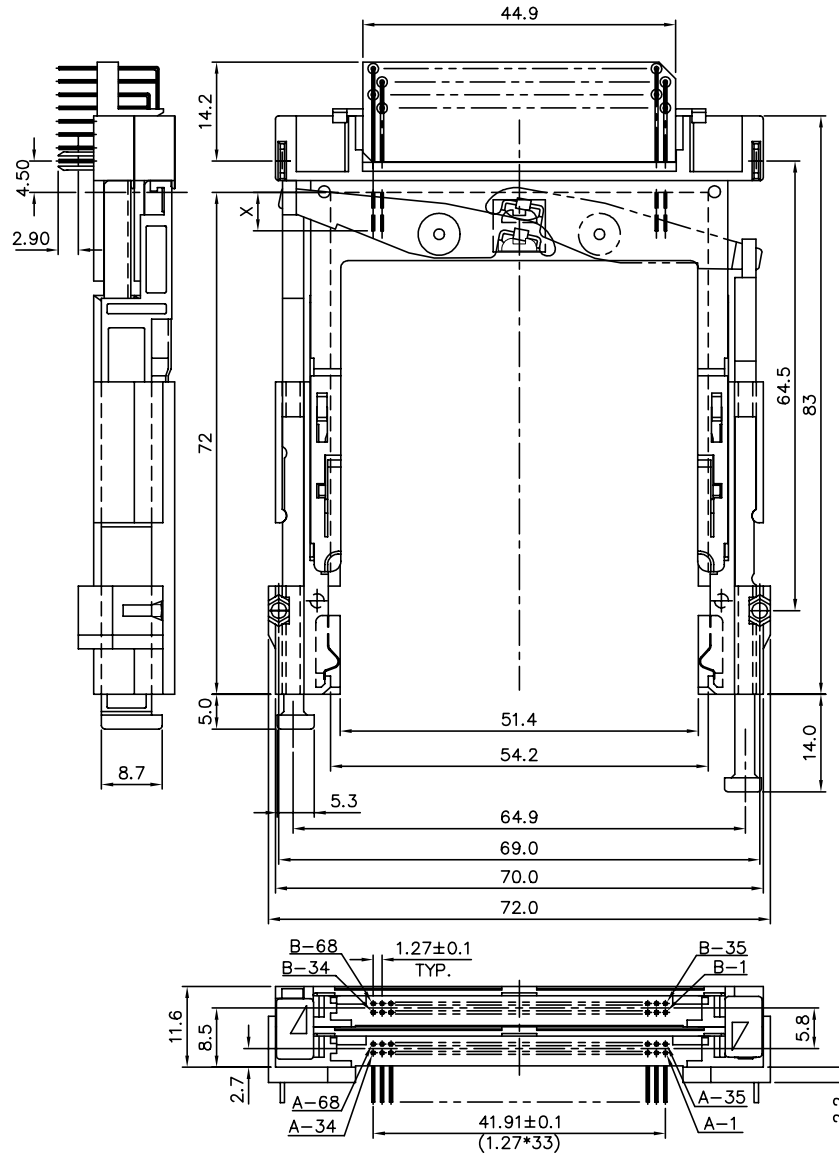
1. EJECT FORCE 3.5 Kg MAX.
2. ASS'Y PROCESS
 - 2.1 TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
3. EJECT TRAVEL: 9.0mm
4. MATERIAL
 - 4.1 PART (A) (HEADER ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN :COPPER ALLOY
 - 4.2 PART (B) (EJECT MECHANISM ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE :STAINLESS
EMI CONTACT:PHOSPHOR BRONZE
5. FINISH (PIN)
 - UNDER PLATING :0.5µm MIN. NI
 - CONTACT AREA :0.076 µm MIN. GOLD
 - SOLDER TAIL : 2.5µm MIN. Sn-Pb
 - : 2.5µm MIN. PURE Sn (FOR -*****LF)
6.

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68
7. NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
8. IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
9. IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
10. LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
11. PRODUCT SPEC: 110-263



mat'l. code	surface ISO1302 ✓	tolerance ISO406 ISO1101	projection	product family PCMCIA
ltr ecn nodr date	tolerances unless otherwise specified		MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
M	angle	0.X±0.3	scale 1.5:1	dwg no 94721
	0°±2'	0.XX±0.13		sheet 11 of 12 size A4
	dr C L FENG	0.XXX±0.05		type Product Customer Drawing
	engr JOSEPH HSIA	04/06/94		
	chr JOSEPH HSIA	04/06/94		
	app'd D K WANG	04/06/94		
sheet index	revision sheet			

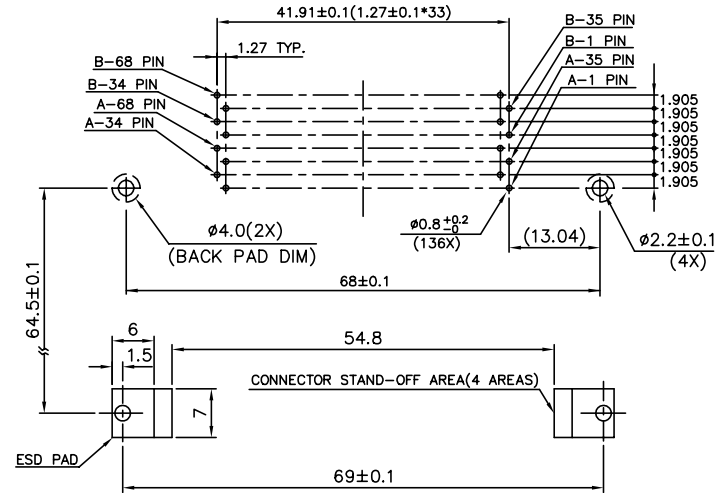
PRODUCT NO.
94721-102CA/102CALF



NOTES:

1. EJECT FORCE 3.5 Kg MAX.
2. ASS'Y PROCESS
 - 2.1 TO MOUNT PART A ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART B WITH TWO SCREWS.
3. EJECT TRAVEL: 9.0mm
4. MATERIAL
 - 4.1 PART A (HEADER ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN :COPPER ALLOY
 - 4.2 PART B (EJECT MECHANISM ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE :STAINLESS
EMI CONTACT:PHOSPHOR BRONZE
5. FINISH (PIN)
 - UNDER PLATING :0.5µm MIN. Ni
 - CONTACT AREA :0.076 µm MIN. GOLD
 - SOLDER TAIL : 2.5µm MIN. Sn-Pb
 - : 2.5µm MIN. PURE Sn (FOR -*****LF)
6.

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68
7. NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
8. IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
9. IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
10. LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
11. PRODUCT SPEC: 110-263



mat'l. code	surface ISO1302	tolerance ISO406 ISO1101	projection	product family PCMCIA
l'tecn nodr date	tolerances unless otherwise specified		MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
M	angle	0.X±0.3	scale:5:1	dwg no 94721
	0°±2'	0.XX±0.13		sheet 2 of 12 size A4
		0.XXX±0.05		type Product Customer Drawing
dr c L FENG 04/06/94	engr JOSEPH HSIA 04/06/94	chr JOSEPH HSIA 04/06/94		
app'd D K WANG 04/06/94				
sheet index	revision sheet			